

J683-VB Datasheet

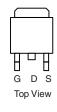
P-Channel 60-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	/ _{DS} (V) R _{DS(on)} (Ω)			
- 60	0.0065 at V _{GS} = - 10 V	- 110		
- 00	0.0085 at V _{GS} = - 4.5 V	- 110		

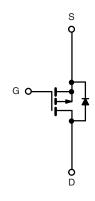
FEATURES

- Trench Power MOSFET
- Package with Low Thermal Resistance
- 100 % R_g Tested





TO-263



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_{C} = 2$	25 °C, unless other	wise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	v	
Gate-Source Voltage		V _{GS}	± 20	v	
Continuous Drain Current ^d	T _C = 25 °C	1-	- 110		
(T _J = 175 °C)	T _C = 125 °C	I _D	- 75	A	
Pulsed Drain Current		I _{DM}	- 200	A	
Avalanche Current	L = 0.1 mH	I _{AS}	- 85		
Single Pulse Avalanche Energy ^d		E _{AS}	211	mJ	
	T _C = 25 °C	В	272 ^c	14/	
Maximum Power Dissipation	T _A = 25 °C ^b	• P _D -	3.75 ^b	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	_	Symbol	Limit	Unit	
Junction-to-Ambient	PCB Mount ^d	R _{thJA}	40	°C/W	
Junction-to-Case		R _{thJC}	0.55	0/10	

Notes:

a. Duty cycle \leq 1 %.

b. When Mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

d. Limited by Package.

* Pb containing terminations are not RoHS compliant, exemptions may apply.

SPECIFICATIONS $T_J = 25^{\circ}$	C, unless o	therwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 V, I_D = -250 \mu A$	- 60			v	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \ \mu A$	- 1		- 3	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1	μΑ	
	I _{DSS}	V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 125 °C			- 50		
		V_{DS} = - 60 V, V_{GS} = 0 V, T_{J} = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = -5 V, V_{GS} = -10 V$	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.0065		- Ω	
	Brach	V_{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.0129			
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.016			
		V _{GS} = - 4.5 V, I _D = - 20 A		0.0085			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 50 A	20			S	
Dynamic ^b		· · · ·					
Input Capacitance	C _{iss}			9200		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$, $V_{DS} = -25 V$, f = 1 MHz		975			
Reverse Transfer Capacitance	C _{rss}	1		760			
Total Gate Charge ^c	Qg			160	240	nC	
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -110 \text{ A}$		40			
Gate-Drain Charge ^c	Q _{gd}			36			
Gate Resistance	Rg	f = 1 MHz	1.5	3	4.5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			20	30	- ns	
Rise Time ^c	t _r	V_{DD} = - 30 V, R _L = 0.27 Ω I _D \cong - 110 A, V _{GEN} = - 10 V, R _G = 2.5 Ω		190	285		
Turn-Off Delay Time ^c	t _{d(off)}			140	210		
Fall Time ^c	t _f			300	450		
Source-Drain Diode Ratings and Cha	aracteristics	T _C = 25 °C ^b					
Continuous Current	ا _S				- 110	A	
Pulsed Current	I _{SM}				- 200		
Forward Voltage ^a	V _{SD}	I _F = - 50 A, V _{GS} = 0 V		- 1.0	- 1.5	V	
Reverse Recovery Time	t _{rr}			60	90	ns	
Peak Reverse Recovery Charge	I _{RM(REC)}	I _F = - 50 A, di/dt = 100 A/μs		- 3	- 4.5	А	
Reverse Recovery Charge	Q _{rr}	1 1		0.09	0.2	μC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

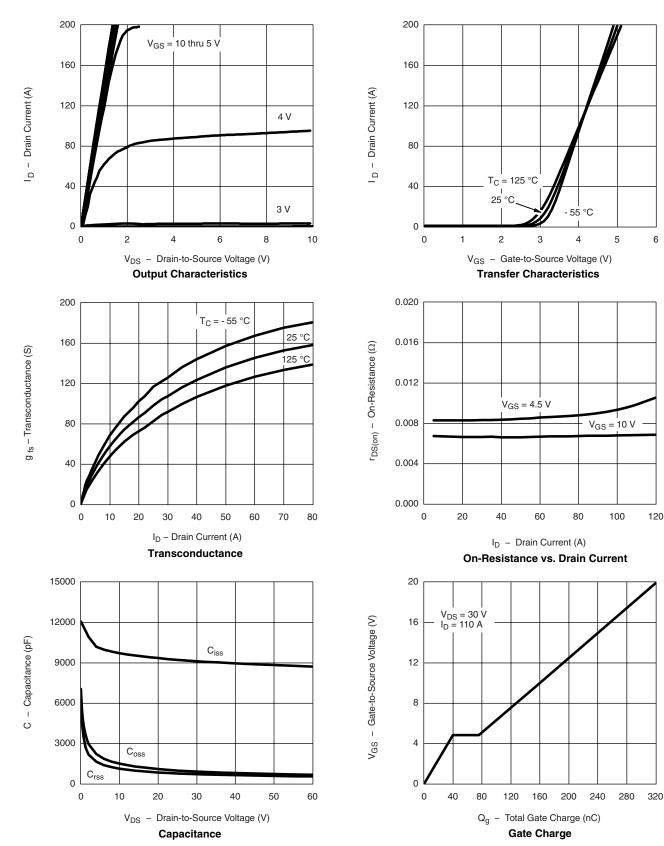
b. Guaranteed by design, not subject to production testing.

c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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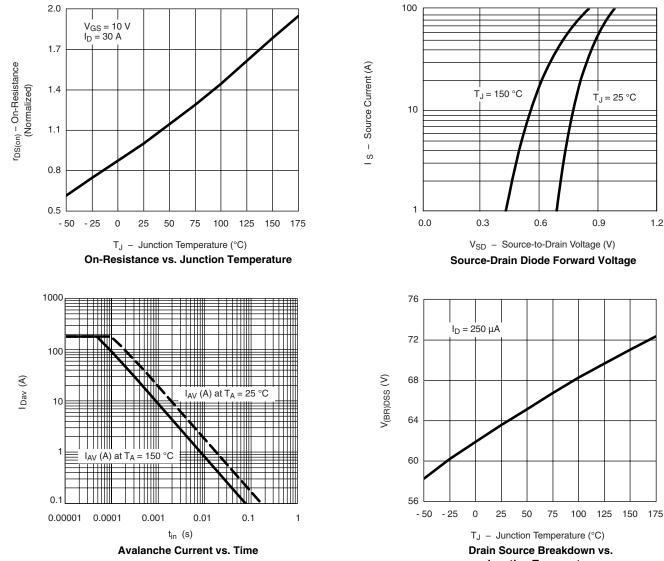


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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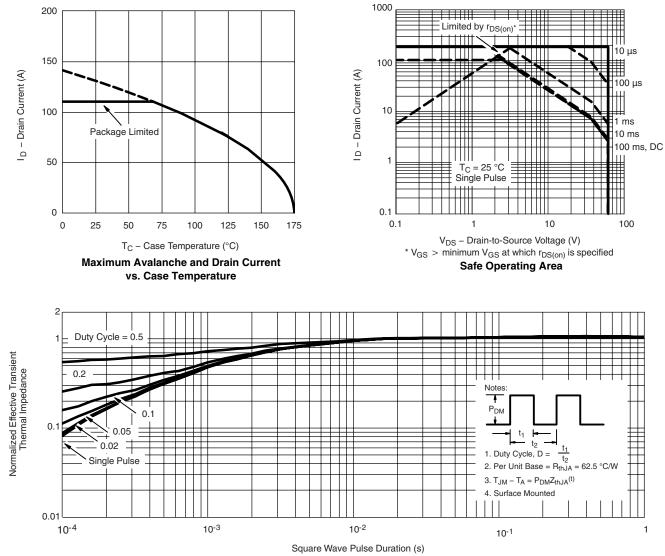
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Junction Temperature



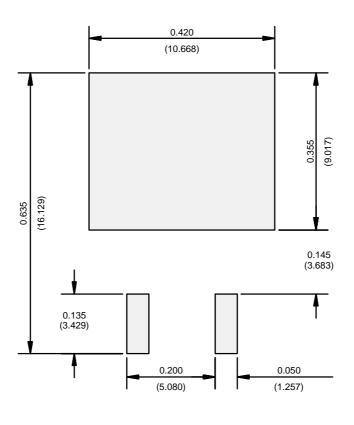
THERMAL RATINGS



Normalized Thermal Transient Impedance, Junction-to-Case



RECOMMENDED MINIMUM PADS FOR D²PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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